

Appl. No. : 10/820,417
Filed : April 7, 2004

AMENDMENTS TO THE CLAIMS

Please cancel claims 1, 5-9, 13-17, 19-22, and 25.

Please rewrite claim 18 in independent form as follows. Insertions are shown underlined while deletions are ~~struck through~~.

1 (canceled)

2-4 (canceled)

5-9 (canceled)

10-12 (canceled)

13-17 (canceled)

18 (currently amended): ~~The~~A method according to ~~Claim 17~~of manufacturing a wiring board comprising:

preparing a composite sheet comprising: (i) a porous film having a top surface and a lower surface and (ii) an adherent sheet containing a thermosetting resin placed on or partially permeated within the top surface of the porous film;

further comprising attaching a releasing resin film to the adherent sheet;
preparing a wiring layer having wiring patterns formed on an insulting insulating layer;

laminating the composite sheet on the wiring layer, said lower surface of the porous film being in contact with said wiring patterns of the wiring layer; and

pressing the adherent sheet under heat, whereby the porous film is deformed to contact both the wiring layer and the insulating layer while the adherent sheet is permeated within the porous film and reaches the wiring layer.

19-22 (canceled)

23-24 (canceled)

25 (canceled)

26 (previously presented): A method of manufacturing a wiring board comprising:

preparing a composite sheet having an adherent sheet containing a thermosetting resin adhered to a porous film or impregnated with at least a part thereof;

laminating at least the composite sheet on a wiring layer having a wiring pattern formed on an insulating layer; and

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heating and pressurizing the laminated product thus obtained or heating and pressurizing it after the pressurization to integrate the laminated product, wherein the composite sheet having a releasing resin film attached to the adherent sheet is used.

27 (previously presented): The method according to Claim 26, wherein the composite sheet having the adherent sheet adhered to a porous film is used and the laminating step is carried out by arranging the porous film side of the composite sheet onto the wiring layer.

28 (previously presented): The method according to Claim 26, wherein the composite sheet having a porous film impregnated with a part of the adherent sheet and the laminating step is carried out by arranging the porous film side of the composite sheet onto the wiring layer.

29 (previously presented): The method according to Claim 26, wherein the composite sheet having a porous film impregnated with the whole adherent sheet is used.